

What is claimed is:

1. A substrate having a repaired metallic pattern whose defective part is repaired by applying a conductive material thereon, wherein the defective part is repaired by a thin film of metal deposited from a metallic organic compound.

2. A substrate having a repaired metallic pattern according to claim 1, wherein said metallic pattern is an electrode.

3. A substrate having a repaired metallic pattern according to claim 1, wherein said metallic pattern is a lightproof film.

4. A substrate having a repaired metallic pattern according to any one of claim 1 to claim 3, wherein said metallic organic compound is gold-resinate-base paste for low temperature baking.

5. A method for repairing a metallic pattern on a substrate, said method comprising steps of:

applying a metallic organic compound to a defective part in a metallic pattern formed on said substrate; and

heating said organic compound to deposit a metallic thin film in said defective part.

6. A method for repairing a metallic pattern on a substrate according to claim 5, wherein energy of laser light radiated from a semiconductor laser is used as a heat source for heating said metallic organic compound.

7. A method for repairing a metallic pattern on a substrate

according to claim 6, wherein said metallic organic compound is provisionally baked and then mainly baked by adjusting the output of said semiconductor laser and is cooled thereafter.

8. A method for repairing a metallic pattern on a substrate according to any one of claim 5 to claim 7, further comprising a step of removing a part sticking out from said metallic pattern of a deposited metallic thin film.

9. A device for repairing a defective part in a metallic pattern formed on a substrate, said device comprising:

a receiving part for holding a metallic organic compound thereon;

a transfer body moving between said receiving part and said defective part in the metallic pattern and transferring the metallic organic compound held on said receiving part to said defective part; and

a semiconductor laser unit for baking said metallic organic compound transferred to said defective part in the metallic pattern.

10. A device for repairing a defective part in a metallic pattern formed on a substrate according to claim 9, further comprising a laser radiating unit for removing a part sticking out from said metallic pattern when said metallic pattern is a lightproof film.

11. A device for repairing a defective part in a metallic pattern formed on a substrate according to claim 9 or claim 10,

wherein said semiconductor laser unit has an output adjusting unit.